

### AMENDMENTS TO THE CLAIMS

Please amend the claims to read as follows. Deletions are shown in ~~strikeout~~ text; additions are underlined.

Please cancel Claims 3, 10, 11, 21, 28, 37, 38 and 48-65 without prejudice. Applicants retain the right to further pursue claims to the cancelled subject matter at a later date.

1. Cancelled
2. (Currently Amended) An illumination module, comprising:
  - a dielectric layer having first and second sides;
  - a ~~plurality of~~ light emitting diodes (LEDs);
  - a plurality of electrically-conductive contacts on the first side of the dielectric layer, ~~each of the plurality of contacts being configured to mount an~~ the LED such that the ~~plurality of LEDs are~~ is electrically connected to the contacts;
  - a heat conductive body on the second side of the dielectric layer;
  - a heat conductive tab comprising a heat conductive surface in communication with the heat conductive body, the heat conductive surface having a surface area substantially greater than a surface area of the heat conductive body;
  - wherein heat from the LEDs is communicated through the contacts, dielectric layer, and heat conductive body to the heat conductive surface.
3. Cancelled
4. (Currently Amended) The illumination module of Claim ~~3~~2, wherein the heat conductive tab behaves as a heat sink.
5. (Previously Presented) The illumination module of Claim 2, wherein heat is dissipated from the heat conductive surface to the surrounding environment.
6. (Previously Presented) The illumination module of Claim 2, wherein the heat conductive body is generally flat.
7. (Previously Presented) The illumination module of Claim 6, wherein the contacts are substantially flat and coplanar relative to each other.
8. (Previously Presented) The illumination module of Claim 7, wherein the body is substantially parallel to the contacts.

9. (Currently Amended) The illumination module of Claim 84, wherein the heat conductive body has a first side and a second side, the first side communicating with the second side of the dielectric layer, and the heat conductive surface is substantially complementary to a the second side surface of the heat conductive body.

10. Cancelled

11. Cancelled

12. (Previously Presented) The illumination module of Claim 9, wherein the heat conductive surface has a thermal conductivity greater than about 100 W/mK.

13. (Previously Presented) The illumination module of Claim 12, wherein the heat conductive surface comprises a metal.

14. (Previously Presented) The illumination module of Claim 13, wherein the heat conductive surface comprises aluminum.

15. (Previously Presented) The illumination module of Claim 12, wherein the body has a thermal conductivity greater than about 100 W/mK.

16. (Previously Presented) The illumination module of Claim 12, wherein the heat conductive surface is substantially rigid.

17. (Previously Presented) The illumination module of Claim 9, wherein the dielectric member is substantially planar.

18. (Currently Amended) The illumination module of Claim 9, wherein the heat conductive surface is significantly larger than ~~a surface~~ the second side of the heat conductive body.

19. (Previously Presented) The illumination module of Claim 2, wherein each of the LEDs comprises a lead, and the leads are configured to be mounted to respective contacts.

20. (Previously Presented) A method of making an illuminated display, comprising:  
providing a housing having at least one wall surface;  
providing a plurality of the illumination modules of Claim 2; and  
mounting the plurality of illumination modules onto the at least one wall surface.

21. Cancelled

22. (Currently Amended) The method of Claim ~~24~~20 additionally comprising mounting an illumination module so that at least a portion of the heat conductive tab is not in contact with the housing wall surface.

23. (Currently Amended) An illumination apparatus, comprising  
a housing;  
a heat conductive tab comprising a heat conductive surface arranged in an interior  
of the housing; and  
an illumination module mounted on the heat conductive surface, the illumination module comprising:

a dielectric having a first side and a second side;

~~at least two~~ a light emitting diodes (LEDs);

a plurality of electrically conductive contacts on the first side of the dielectric, ~~each of the plurality of contacts being configured to mount a lead of the~~ an LED such that the LEDs are is electrically connected to the contacts; and

a heat conductive body on the second side of the dielectric;

wherein heat from the LEDs flows through the contacts and dielectric to the heat conductive body, and from the body to the heat conductive surface.

24. (Currently Amended) The apparatus of Claim 23, wherein the contacts communicate heat to the heat conductive body through a first thermal engagement area, and an engagement surface of the body communicates heat to the heat conductive surface through a second thermal engagement area that is larger than the first thermal engagement area, and the heat conductive surface is significantly larger than a—the engagement surface of the heat conductive body.

25. (Currently Amended) The apparatus of Claim ~~23~~24, wherein the heat conductive body contacts the heat conductive surface.

26. (Previously Presented) The apparatus of Claim 23, wherein the housing comprises a wall surface, and the heat conductive surface is attached to the wall surface.

27. (Previously Presented) The apparatus of Claim 23, wherein the heat conductive body is substantially flat.

28. Cancelled

29. (Currently Amended) The apparatus of Claim 28~~23~~, wherein the heat conductive tab is larger than the heat conductive body.

30. (Previously Presented) The apparatus of Claim 29, wherein the heat conductive surface is substantially flat.

31. (Previously Presented) The apparatus of Claim 29, wherein the heat conductive tab comprises a material having a thermal conductivity greater than about 100 W/mK.

32. (Currently Amended) The apparatus of Claim 28~~23~~, wherein the housing comprises a wall surface, and at least a portion of the heat conductive surface is spaced from the wall surface.

33. (Previously Presented) The apparatus of Claim 32, wherein the heat conductive surface is configured to draw LED-generated heat from the module for dissipation in the housing.

34. (Currently Amended) An illumination apparatus, comprising:  
a housing comprising ~~The apparatus of Claim 23, wherein the housing comprises~~  
a plurality of wall surfaces that define a channel;  
a heat conductive surface arranged in an interior of the housing; and  
an illumination module mounted on the heat conductive surface, the illumination  
module comprising:  
a dielectric having a first side and a second side;  
a light emitting diode (LED);  
a plurality of electrically conductive contacts on the first side of the  
dielectric, each of the plurality of contacts being configured to mount a lead of the  
LED such that the LED is electrically connected to the contacts; and  
a heat conductive body on the second side of the dielectric;  
wherein heat from the LED flows through the contacts and dielectric to the heat  
conductive body, and from the body to the heat conductive surface.

35. (Previously Presented) The apparatus of Claim 34, wherein a translucent cover extends over the channel.

36. (Currently Amended) The apparatus of Claim 35, wherein heat from the LEDs is drawn to the heat conductive surface and dissipated from the surface into the channel.

37. Cancelled

38. Cancelled

39. (Currently Amended) An illumination apparatus, module for mounting on a heat conducting surface that is larger than the module, the module comprising:

a heat conductive body having a first side and a second side;

a thin dielectric portion on a first side of the heat conductive body;

a plurality of light emitting diodes (LEDs); and

a plurality of electrically-conductive contacts on a first side of the dielectric portion, the LEDs being mounted to the contacts such that the LEDs are electrically connected to one another, the contacts thermally communicating with the dielectric portion through a first thermal communication area between the contacts and the first side of the dielectric portion;

wherein a second side of the dielectric portion is arranged on the first side of the heat conductive body so that the first side of the body is in thermal communication with the contacts through the dielectric portion; ~~and~~

wherein the first side of the body has a surface area larger than the thermal communication area;

a heat conducting surface;

~~and wherein~~ the second side of the body has a surface generally complementary to the heat conducting surface, and the second side of the body thermally communicates with the heat conducting surface through a second thermal communication area between the body and the heat conducting surface to provide thermally conductive contact with the heat conducting surface; and

wherein the second thermal communication area has a greater area than the first thermal communication area;

whereby heat is thermally conducted from the LEDs to the heat conducting surface.

40. (Previously Presented) The illumination module of Claim 39, wherein the second side of the body has a generally flat surface.

41. (Previously Presented) The illumination module of Claim 40, wherein the contacts are substantially flat and coplanar relative to each other.

42. (Previously Presented) The illumination module of Claim 41, wherein a first side of the body is substantially flat and parallel to the contacts.

43. (Previously Presented) The illumination module of Claim 42, wherein the dielectric portion is substantially flat.

44. (Previously Presented) The illumination module of Claim 39, wherein the heat conductive body has a thermal conductivity greater than about 100 W/mK.

45. (Previously Presented) The illumination module of Claim 39, wherein the heat conductive surface has a thermal conductivity greater than about 100 W/mK.

46. (Currently Amended) An illumination module for mounting on a heat conducting surface that is larger than the module, the module comprising:

a heat conductive body having a first side and a second side;

a thin dielectric portion on a first side of the heat conductive body;

a plurality of light emitting diodes (LEDs); and

a plurality of electrically-conductive contacts on a first side of the dielectric portion, the LEDs being mounted to the contacts such that the LEDs are electrically connected to one another, the contacts thermally communicating with the dielectric portion through a thermal communication area between the contacts and the first side of the dielectric portion;

wherein a second side of the dielectric portion is arranged on the first side of the heat conductive body so that the first side of the body is in thermal communication with the contacts through the dielectric portion; and

wherein the first side of the body has a surface area larger than the thermal communication area, and the second side of the body has a surface generally complementary to the heat conducting surface to provide thermally conductive contact with the heat conducting surface;

whereby heat is thermally conducted from the LEDs to the heat conducting surface; and additionally ~~The illumination module of Claim 39,~~ comprising a heat conductive tab that comprises the heat conductive surface.

47. (Previously Presented) The illumination module of Claim 46, wherein the heat conductive tab is larger than the heat conductive body.

48-65. Cancelled

Please add the following new claims:

66. (New) The illumination module of Claim 9, wherein the body is connected to the heat conductive surface so that heat flows from substantially the entire second side of the body to the heat conductive surface.

67. (New) The illumination module of Claim 66, wherein the second side of the body is attached substantially flush to the heat conductive surface by an adhesive.

68. (New) The illumination module of Claim 18, wherein substantially the entire second side of the body communicates with the heat conductive surface.

69. (New) The apparatus of Claim 24, wherein the engagement surface of the heat conductive body is connected to the heat conductive surface via an adhesive.

70. (New) The apparatus of Claim 69, wherein substantially the entire engagement surface engages the heat conductive surface so that the second thermal engagement area is substantially the same as the engagement surface area.

71. (New) The apparatus of Claim 34 additionally comprising a heat sink within the housing, and the heat conductive surface is integrally formed with the heat sink.

72. (New) The apparatus of Claim 71, wherein the heat conductive surface is generally flat, and at least a portion of the heat sink extends at an angle relative to the heat conductive surface.

73. (New) An illumination device, comprising:

a light emitting diode (LED) module in combination with a heat sink member, the LED module attached to the heat sink member, the LED module comprising:

at least one LED;

a dielectric layer having first and second sides;

plural electrically-conductive contacts on the first side of the dielectric layer, the contacts being configured to mount the at least one LED such that the at least one LED is electrically connected to the contacts; and

a heat conductive body having a first and second face, the first face being on the second side of the dielectric layer, the body being in thermal

communication with the plural contacts through the dielectric layer, the first face having a surface area at least the same as an aggregate surface area of one side of the contacts;

wherein the second face of the heat conductive body is attached to the heat sink member so that heat flows from the body to the heat sink member, at least an engagement portion of the second face conducting heat flow from the body to the heat sink, the engagement portion having a surface area at least the same as the aggregate surface area of one side of the contacts;

wherein the heat sink member has a surface area greater than a surface area of the heat conductive body.

74. (New) An illumination device as in Claim 73, wherein the heat sink member has a mount portion configured to accept the LED module, and the LED module is attached to the mount portion.

75. (New) An illumination device as in Claim 74, wherein the mount portion is integrally formed with the heat sink member.

76. (New) An illumination device as in Claim 75, wherein the mount portion is disposed at an angle relative to an adjacent portion of the heat sink member.

77. (New) An illumination device as in Claim 75, wherein the LED module is fastened to the mount portion using rivets.

78. (New) An illumination device as in Claim 75, wherein the LED module is fastened to the mount portion by an adhesive.

79. (New) An illumination device as in Claim 78, wherein the adhesive comprises a heat conductive adhesive.

80. (New) An illumination device as in Claim 78, wherein the heat conductive body comprises a flat aluminum plate.

81. (New) An illumination device as in Claim 80, wherein substantially the entire second face of the body portion is connected to the mount portion.

82. (New) An illuminated display apparatus, comprising:

a plurality of the illumination devices recited in Claim 73 electrically connected to one another in an electrically parallel arrangement; and



a display member having a wall surface;

wherein at least one of the plurality of illumination devices is arranged on the wall surface.

83. (New) An illumination device as in Claim 82, comprising a pair of electrical supply wires, wherein each of the plurality of illumination devices is electrically connected to the pair of electrical supply wires.

84. (New) An illumination device as in Claim 83, wherein the illumination devices employ insulation displacement connectors to electrically connect to the pair of electrical supply wires.

85. (New) An illuminated display apparatus as in Claim 82, wherein the display member comprises a channel defined by a plurality of walls, and the illumination devices are disposed within the channel.

86. (New) An illuminated display apparatus as in Claim 83, wherein the wall surface is configured to function as a heat sink.

87. (New) An illumination apparatus, comprising:

an illumination device as recited in Claim 73; and

a housing, the housing having an outlet aperture and being attached to the heat sink member so as to generally enclose the LED module;

wherein the apparatus is adapted so that light from the LED module is directed out of the housing aperture.

88. (New) An illumination apparatus as in Claim 87 additionally comprising an optical element for directing light from the LED module in a desired direction.

89. (New) An illumination apparatus as in Claim 88, comprising a lens.

90. (New) An illumination apparatus as in Claim 88, comprising at least one reflector.

91. (New) An illumination apparatus, comprising:

a substantially enclosed housing comprising a housing wall and a light-transmissive portion;

a heat sink having a mount portion, the mount portion disposed within the enclosed housing;

a lighting module comprising:

a light emitting diode (LED);

a dielectric having first and second sides;

plural electrically-conductive contacts on the first side of the dielectric, the contacts being configured to mount the LED so that the LED is electrically connected to the contacts; and

a heat conductive body on the second side of the dielectric;

wherein the heat conductive body is attached to the mount portion so that heat from the LED flows through the dielectric to the heat conductive body, and from the body to the heat sink via the mount portion.

92. (New) The apparatus of Claim 91, wherein the heat conductive body has opposing first and second faces, the first face being connected to the dielectric, and the second face being connected to the heat sink mount portion.

93. (New) The apparatus of Claim 92, wherein substantially the entire second face is connected to the mount portion.

94. (New) The apparatus of Claim 92, wherein the body is connected to the mount portion using a mechanical fastener.

95. (New) The apparatus of Claim 92, wherein the body is connected to the mount portion by an adhesive.

96. (New) The apparatus of Claim 92, wherein the mount portion is integrally formed with the heat sink.

97. (New) The apparatus of Claim 96, wherein the mount portion is disposed at an angle relative to an adjacent portion of the heat sink.

98. (New) The apparatus of Claim 91, wherein the apparatus comprises a plurality of lighting modules, and additionally comprising a pair of electrical supply wires, an elongate portion of the pair of electrical supply wires arranged within the housing, wherein each of the lighting modules is electrically connected to the elongate portion of the pair of electrical supply wires.

99. (New) The apparatus of Claim 98, wherein the lighting modules employ insulation displacement connectors to electrically connect to the pair of electrical supply wires.

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100. (New) The apparatus of Claim 91, wherein the contacts thermally communicate with the dielectric through a thermal communication area between the contacts and the first side of the dielectric, and the body comprises first and second sides, the first side being connected to the second side of the dielectric, the second side of the body being connected to the mount portion, and a thermal communication area between the second side of the body and the mount portion is greater than the thermal communication area between the contacts and the first side of the dielectric.